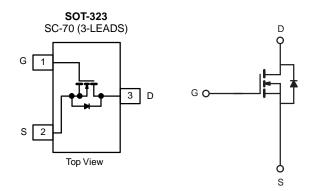


AP1332GEU-HF-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
	0.036 at V_{GS} = 10 V	4				
20	0.040 at V _{GS} = 4.5 V	3.8	4 nC			
	0.048 at V_{GS} = 2.5 V	3.6				



FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Portable Devices
 - Load Switch
 - Battery Switch
- · Load Switch for Motors, Relays and Solenoids

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, unl	ess otherwis	e noted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	20	v
Gate-Source Voltage		V _{GS}	± 12	v
	T _C = 25 °C		4 ^a	
Continuous Drain Current (T = $150 ^{\circ}$ C)	T _C = 70 °C		3.6 ^a	-
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	4 ^{a, b, c}	-
	T _A = 70 °C		3.7 ^{b, c}	А
Pulsed Drain Current (t = 300 µs)		I _{DM}	20	
Continuous Source-Drain Diode Current	T _C = 25 °C		2.3 ^a	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.3 ^{b, c}	
	T _C = 25 °C		2.8	
Maximum Power Dissipation	T _C = 70 °C	PD	1.8	w
	T _A = 25 °C	ГD	1.56 ^{b, c}	vv
	T _A = 70 °C		1.0 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	60	80	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	34	45	C/W		

Notes:

a. Package limited, $T_C = 25$ °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 125 °C/W.

COMPLIANT HALOGEN

FREE



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20			V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	- Ι _D = 250 μΑ		23		mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 3.2		mv/ C		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.6		1.3	V		
Gate-Source Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 4.5 V			± 0.5	μA		
		$V_{DS} = 0 V, V_{GS} = \pm 12 V$			± 25			
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1			
Zero Gale voltage Drain Gurrent	IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	15			А		
		V _{GS} = 10 V, I _D = 3.7 A		0.036		Ω		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 3.6 A		0.040				
		V _{GS} = 2.5 V, I _D = 1.5 A		0.048				
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 3.7 A		17		S		
Dynamic ^b				•		•		
Takal Oaka Okaana		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$		8.8	13.5	13.5 6 nC		
Total Gate Charge	Qg			4	6			
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 3.7 \text{ A}$		0.9				
Gate-Drain Charge	Q _{gd}			1.1				
Gate Resistance	Rg	f = 1 MHz	0.4	2	4	kΩ		
Turn-On Delay Time	t _{d(on)}			0.29	0.58	-		
Rise Time	t _r	V _{DD} = 15 V, R _I = 4.1 Ω		0.4	0.8			
Turn-Off DelayTime	t _{d(off)}	$I_D \approx 3.7$ Å, $V_{GEN} = 4.5$ V, $R_g = 1 \Omega$		1.9	3.8			
Fall Time	t _f	1		0.75	1.5	1		
Turn-On Delay Time	t _{d(on)}			0.1	0.2	μs		
Rise Time	t _r	V _{DD} = 15 V, R _I = 4.1 Ω		0.15	0.3	-		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 3.7 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		3	6			
Fall Time	t _f	1		0.75	1.5			
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.3			
Pulse Diode Forward Current	I _{SM}				20	- A		
Body Diode Voltage	V _{SD}	I _S = 3.7 A, V _{GS} = 0 V		0.85	1.2	V		
Body Diode Reverse Recovery Time	t _{rr}		1	12	25	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 3.7 \text{ A, dl/dt} = 100 \text{ A/}\mu\text{s, } T_J = 25 \text{ °C}$		5	10	nC		
Reverse Recovery Fall Time	t _a			6.5		ns		
Reverse Recovery Rise Time	t _b			5.5				

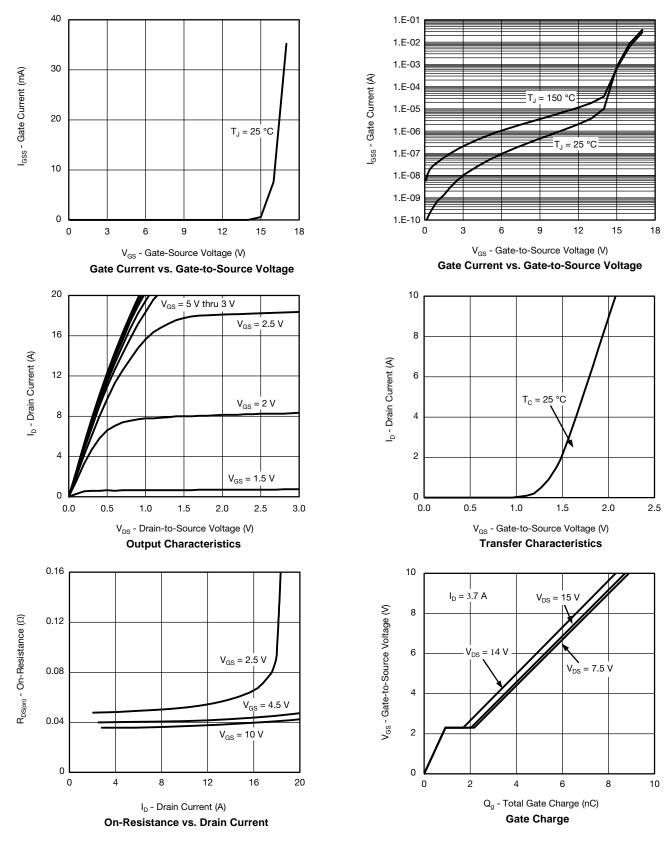
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

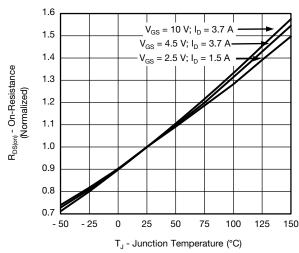
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



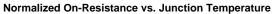
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

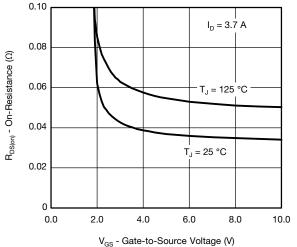




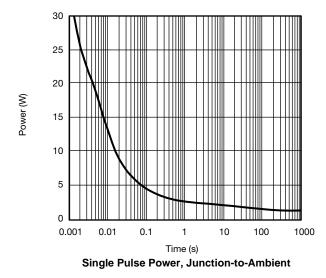


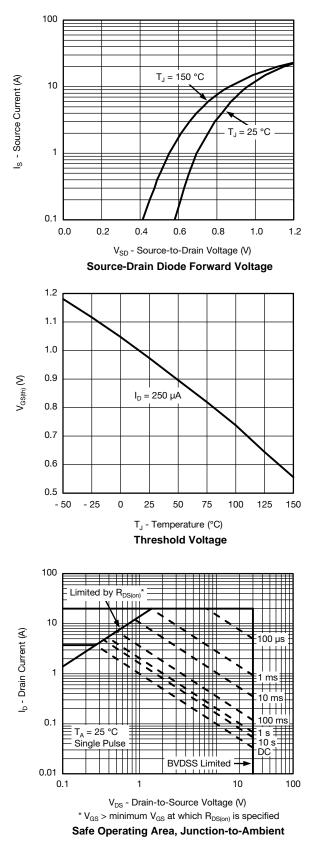
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)





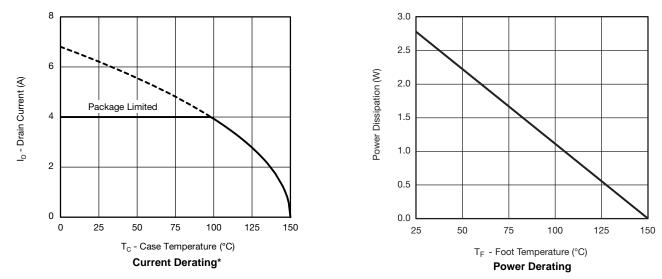








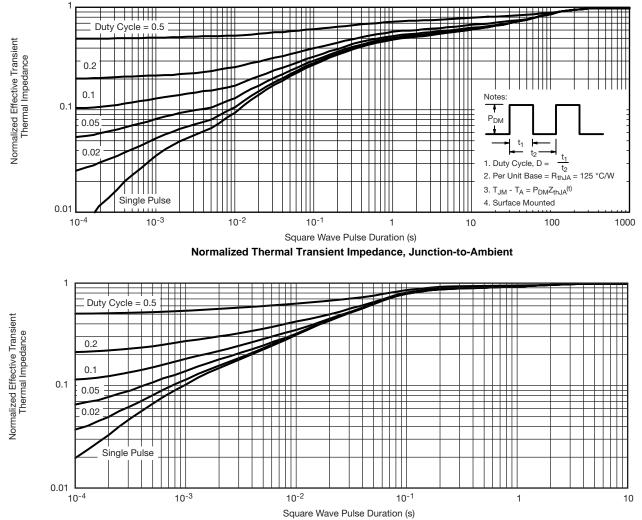
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

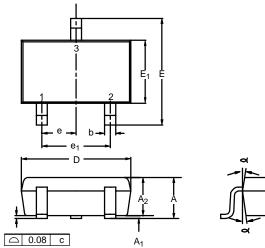


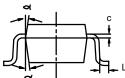
Normalized Thermal Transient Impedance, Junction-to-Foot

AP1332GEU-HF-VB



SC-70: 3-LEADS



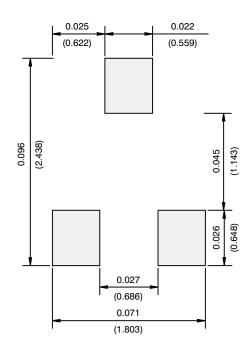


	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	-	0.043
A ₁	-	-	0.10	-	-	0.004
A ₂	0.80	-	1.00	0.031	-	0.039
b	0.25	-	0.40	0.010	-	0.016
С	0.10	-	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC				0.026BSC	;
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
a	7°Nom			7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						

AP1332GEU-HF-VB



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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